



PIONEERS IN
COLLABORATIVE
RESEARCH®



Overview of the Nanoelectronics Research Initiative:

An Industry-Government-University Innovation Partnership

Dr. Jeff Welser

Director, SRC Nanoelectronics Research Initiative

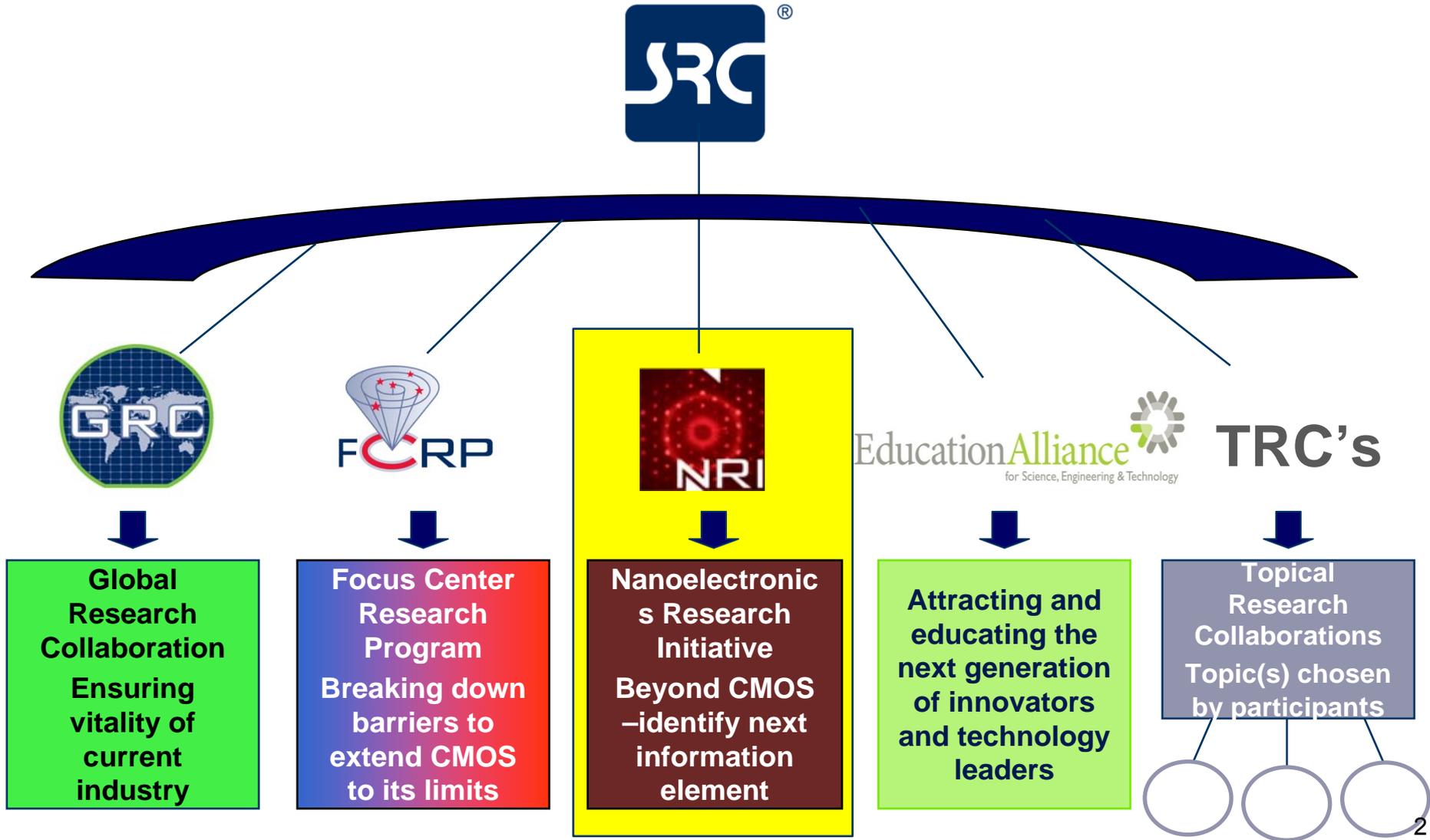
IBM Almaden Research Center

May, 2009

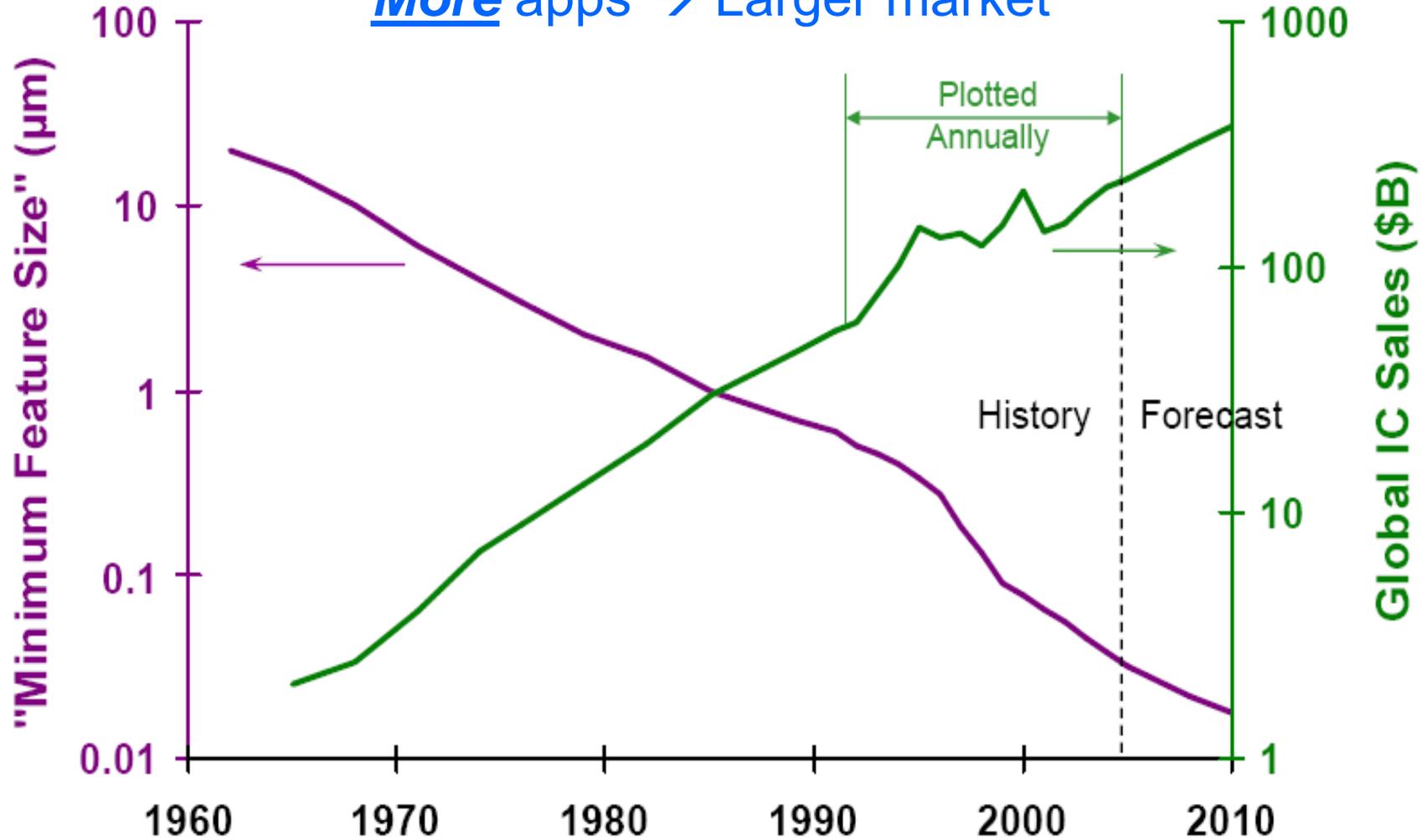


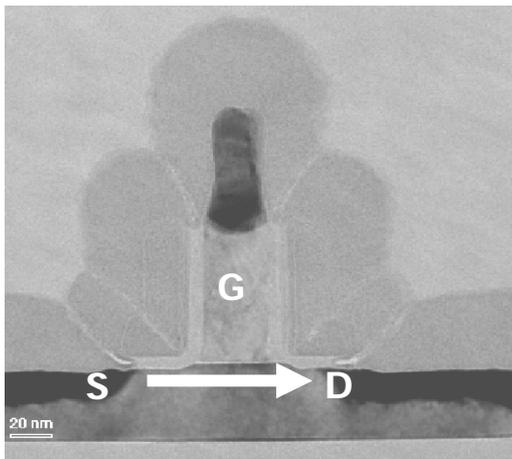
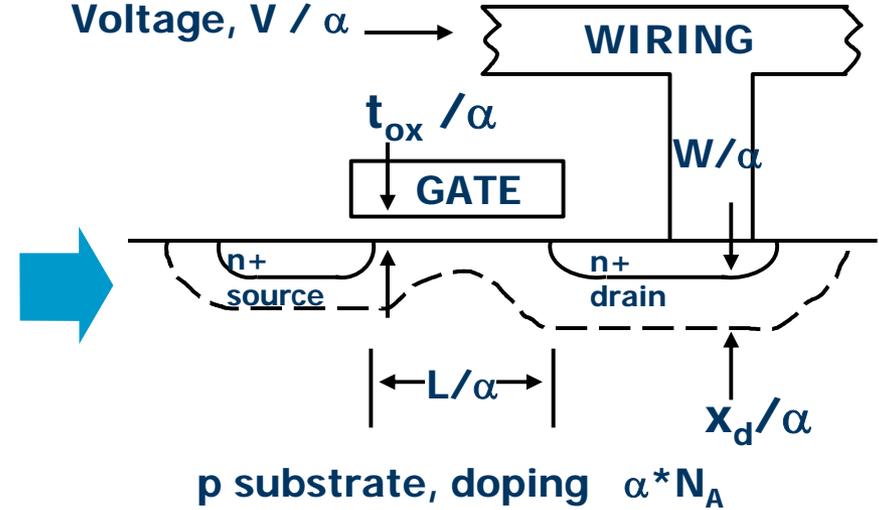
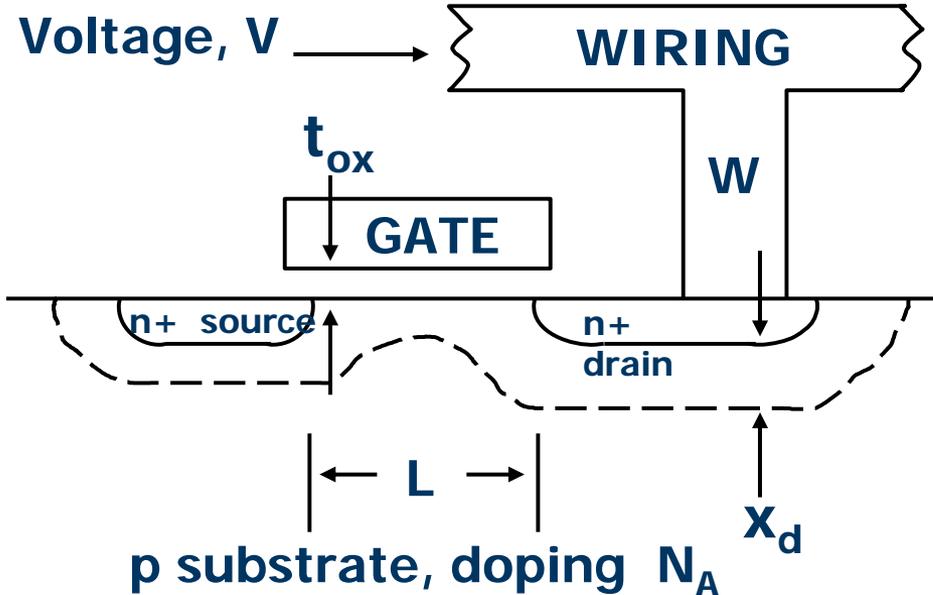
Semiconductor Research Corporation

A Family of Distinct, Related Program Entities



Smaller features → Better performance & cost/function → More apps → Larger market

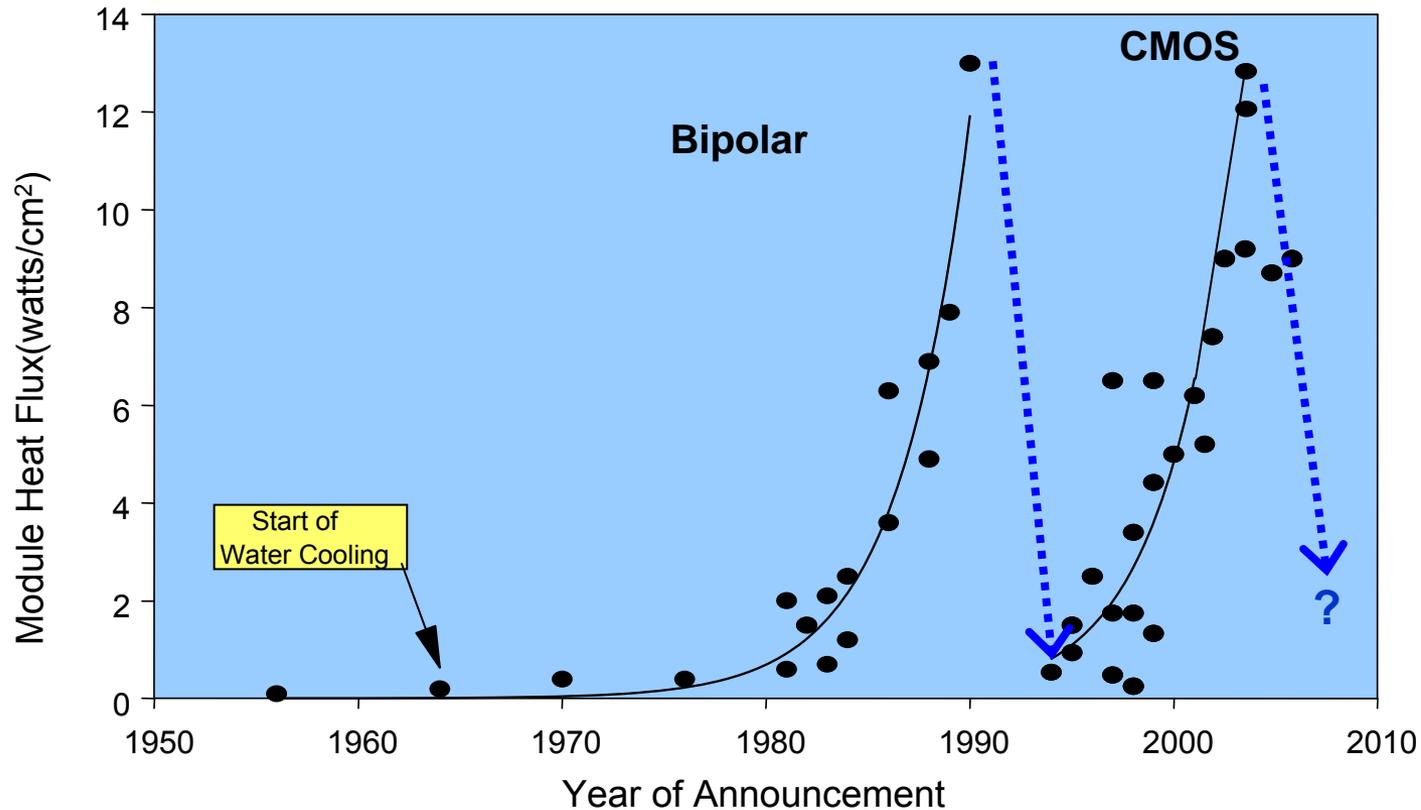




RESULTS:

Higher Density:	α^2
Higher Speed:	α
Lower Power:	$1/\alpha^2$
per circuit	
Power Density:	Constant

- **Circuit heat generation is the main limiting factor for scaling of device speed and switch circuit density**
- Scaling to molecular dimensions may not yield performance increases
 - We will be forced to trade-off between speed and density
- Optimal dimensions for electronic switches should range between 5 and 50 nm
 - Likely achievable with Si – easily within the scope of ITRS projections
- Going to other materials for FETs will likely achieve only “one-time” percentage gains
- ***Need a new device mechanism or computation architecture to enable a new scaling path***



- 2005 ~ 2015: New technology enhancements
 - Continued CMOS shrinking, multi-core chips, 3D packaging, new memory devices, etc.
- > 2015? : New device? → NRI's Goal

- **NRI Mission: Demonstrate novel computing devices capable of replacing the CMOS FET as a logic switch in the 2020 timeframe.**
 - These devices should **show significant advantage over ultimate FETs** in power, performance, density, and/or cost to enable the semiconductor industry to **extend the historical cost and performance trends** for information technology.
 - To meet these goals, NRI pursues **five research vectors**, focused on discovering and demonstrating new devices and circuit elements for doing computation.
 - Finally, it is desirable that these technologies be **capable of integrating with CMOS**, to allow exploitation of their potentially complementary functionality in heterogeneous systems and to enable a smooth transition to a new scaling path.

- **To beat the power problem requires:**
 - A device with a lower energy, room temperature switching mechanism
or
 - A system that operates out of equilibrium or recovers operation energy as part of the logic computation

- **Required characteristics:**

- Scalability
- Performance
- Energy efficiency
- Gain
- Operational reliability
- Room temp. operation

- **Preferred approach:**

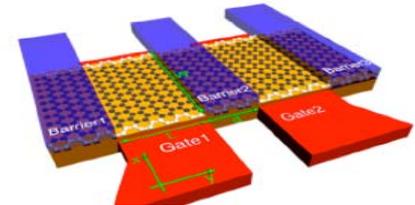
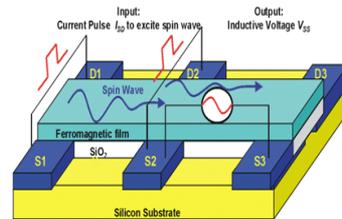
- CMOS process compatibility
- CMOS architectural compatibility



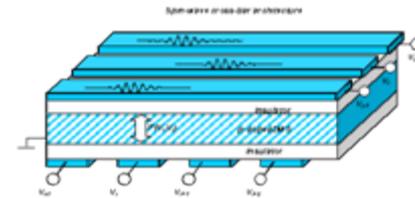
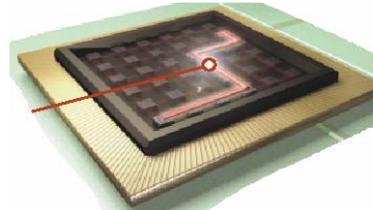
Alternative state variables

- Spin–electron, nuclear, photon
- Phase
- Quantum state
- Magnetic flux quanta
- Mechanical deformation
- Dipole orientation
- Molecular state

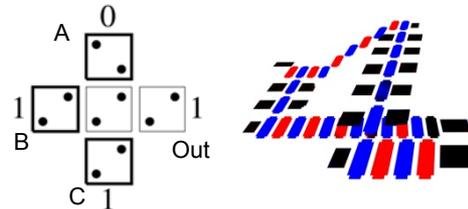
- NEW DEVICE
Device with alternative state vector



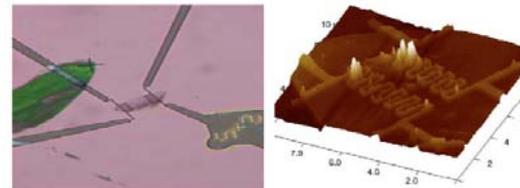
- NEW WAYS TO CONNECT DEVICES
Non-charge data transfer



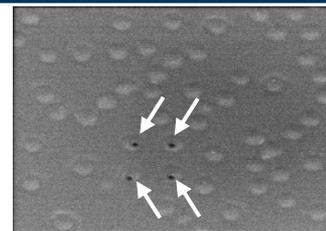
- NEW METHODS FOR COMPUTATION
Non-equilibrium systems



- NEW METHODS TO MANAGE HEAT
Nanoscale phonon engineering



- NEW METHODS OF FABRICATION
Directed self-assembly devices





Nanoelectronics Research Initiative Milestones



■ 2001-2004: Defining Research Needs

- ITRS-Emerging Research Device Technical Working Group
- NSF-SRC Ind-Academia-Govt "Silicon Nanoelectronics and Beyond" Workshops
- SIA Technology Strategy Committee workshops
- *Defined 13 Research Vectors for finding the "next switch"*
- *SIA Board passes resolution for formation of NRI*

■ Current Member Companies:



- Sep 2005: First NRI and NRI-NSF Solicitations released
- Jan 2006: Research Programs started



- Sep 2007: NIST joins NRI



- NRI partnership model highlighted in as sidebar in the National Nanotechnology Initiative (NNI) Strategic Plan (NNCO, 1/08)



NRI Funded Universities

NLST



Nanoelectronics • Architectures



★ Notre Dame
Illinois-UC
Michigan
Cornell

Purdue
Penn State
UT-Dallas
GIT



★ SUNY-Albany
Purdue
Caltech
Yale

GIT
RPI
MIT
UVA

Harvard
Columbia
NCSU



★ UC Los Angeles
UC Berkeley
UC Irvine
UC Santa Barbara
Stanford
U Denver
Portland State
U Iowa



★ UT-Austin
UT-Dallas
U. Maryland

Rice
ASU
NCSU

Texas A&M
Notre Dame
Illinois UC

Columbia
Harvard
Purdue
UVA
Yale
UC Santa Barbara
Stanford
Notre Dame
U. Nebraska/Lincoln
U. Maryland
Cornell
Illinois-UC
Caltech



Over 30 Universities in 18 States



NSF-NRI Projects

Co-funding Projects at NSF Nanoscience Centers



Columbia NSEC	<i>2008: Novel Device Arch. based on Quantum Transport Phenomena in Graphene</i>
Harvard NSEC	<i>2008: Tunable Ultra-fast Conductance Switching through External Fields</i>
Purdue NCN	<i>2007: Exploratory Theory, Modeling, and Simulation for the NRI 2008: Experimental Realization of Low-power Transistors with Negative Capacitors</i>
UVA MRSEC	<i>2007: Coherent Spin Dynamics in Single Ion-doped Semiconductors: Towards a Coherent or Quantum Spin Switch</i>
U. Nebraska MRSEC	<i>2007: Multiferroic Interfaces: New Paradigms for Functional Switching</i>
Yale MRSEC	<i>2007: Design and Fab of Magnetic-based Devices with Complex Oxide Materials</i>
Maryland MRSEC	<i>2007: Pseudospintronics (UT-Austin) 2008: Controlling the Electronic Properties of Graphene</i>
Cornell NSEC	<i>2007: Controlled Orbital Hybridization in the CNT Quantum-Modulated Transistor</i>
Stanford NSEC	<i>2008: Ultra-Low Power Pseudospintronic Switching in Bilayer Graphene at Room T</i>
Caltech MRSEC	<i>2008: Graphene Atomic Switches for Ultracompact Logic Devices and NV Memory</i>

- Funding 12 projects at 10 centers
 - Will announce more projects for 2009 shortly



NRI-NIST Interaction:

Full Partners in NRI Centers



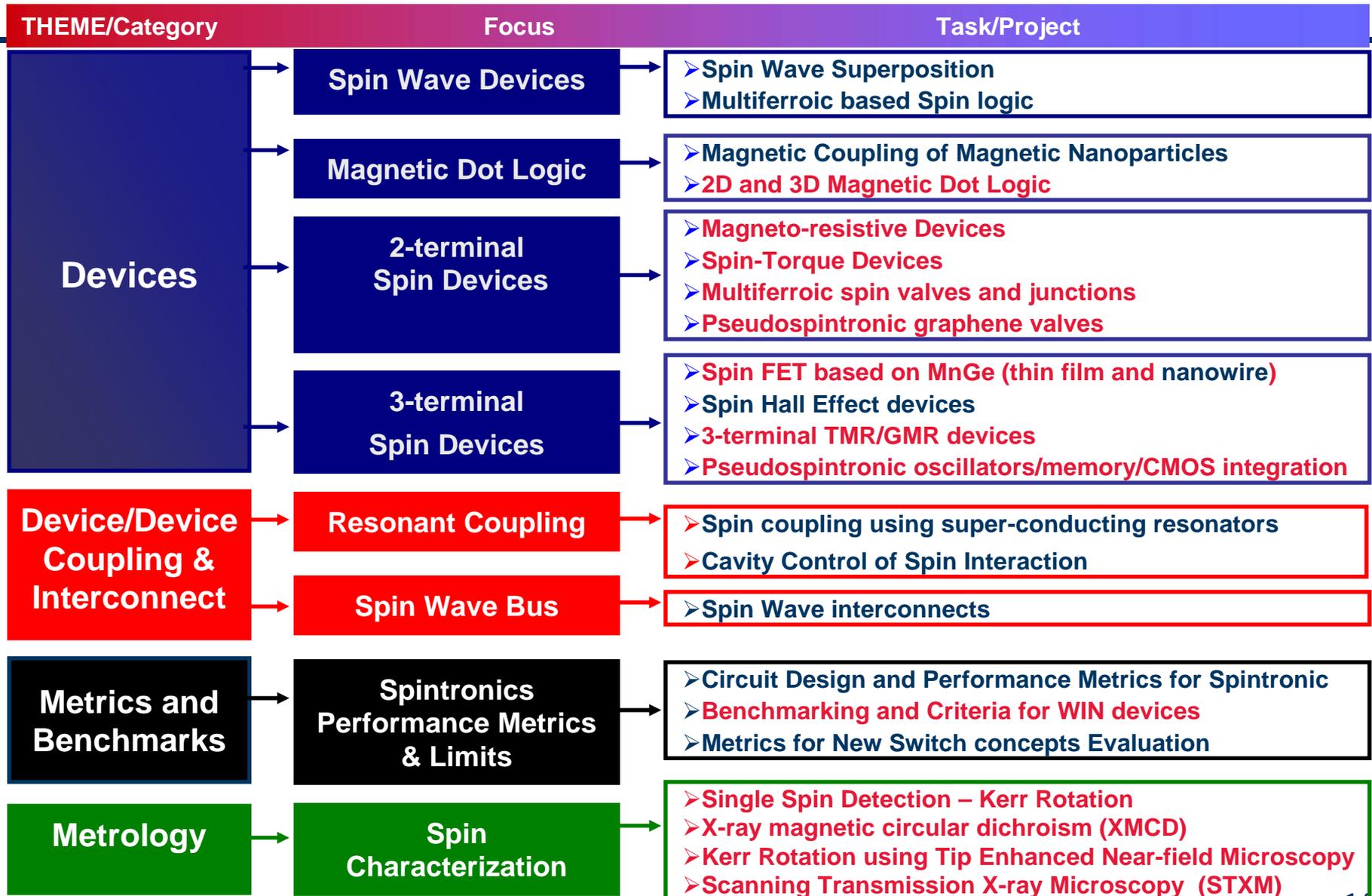
- Leveraging industry, university, and both state & fed government funds, and driving university nanoelectronics infrastructure

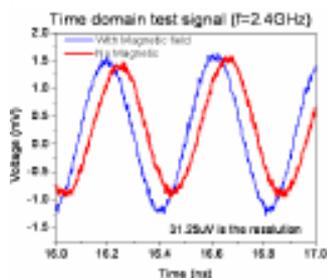


WIN Western Institute of Nanoelectronics	INDEX Institute for Nanoelectronics Discovery & Exploration	SWAN SouthWest Academy for Nanoelectronics	MIND Midwest Institute for Nanoelectronics Discovery
UCLA , UCSB, UC-Irvine, Berkeley, Stanford, U Denver, Iowa, Portland State	SUNY-Albany , GIT, RPI, Harvard, MIT, Purdue, Yale, Columbia, Caltech, NCSU, UVA	UT-Austin , UT-Dallas, TX A&M, Rice, ASU, Notre Dame, Maryland, NCSU, Illinois-UC	Notre Dame , Purdue, Illinois-UC, Penn State, Michigan, UT-Dallas, Cornell, GIT
Theme 1: Spin devices Theme 2: Spin circuits Theme 3: Benchmarks & metrics Theme 4: Spin Metrology	Task I: Novel state-variable devices Task II: Fabrication & Self-assembly Task III: Modeling & Arch Task IV: Theory & Sim Task V: Roadmap Task VI: Metrology	Task 1: Logic devices with new state-variables Task 2: Materials & structs Task 3: Nanoscale thermal management Task 4: Interconnect & Arch Task 5: Nanoscale characterization	Theme 1: Graphene device: Thermal, Tunnel, and Spin Theme 2: Interband Tunnel Devices Theme 3: Non-equilibrium Systems Model / Meas. Theme 4: Nanoarchitecture

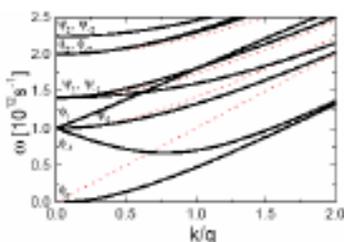
- NIST partnership expanding with joint project collaborations
 - Starting new projects and influencing existing NIST collaborations

PI	Center	Project	NIST Collaborator
Eric Pop		Avalanche impact ionization in semiconducting carbon nanotubes	Curt Richter
Karl Berggren		He Ion Microscope	Mike Postek
Alain Diebold		Optical measurement of Phonons in Graphene and their connection to electron mean free path	Ward Johnson Vinod Tewary
Robert Geer		Nanoscale electrical measurements and SPM of Graphene	Joe Kopanski
Julia Greer		Graphene mechanical properties	Ward Johnson
Phillip First		Atomic-scale electrical metrologies specifically for graphene	Joseph A. Stroscio; Mark D. Stiles
Philip Kim		Studying quantum Hall effect in graphene as a resistance standard	David Newell

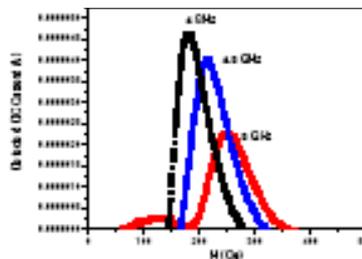




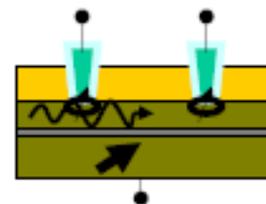
Modulation of spin wave by magnetic field



Simulation of spin wave generation by electric field (UC Berkeley)



Demonstration of Spin Rectification via spin valve (UCLA)

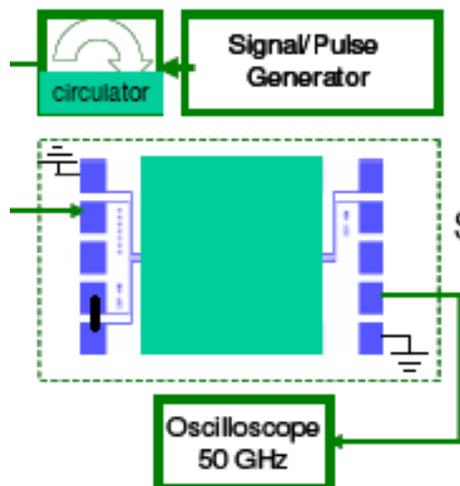


Spin Wave amplification (Stafford)

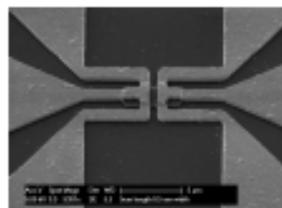
2006

2007

2008/09



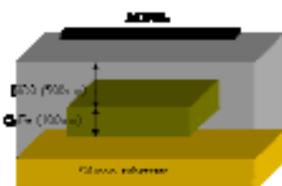
Established spin wave characterization



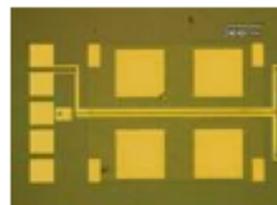
Spin Waveguides (UCSB)



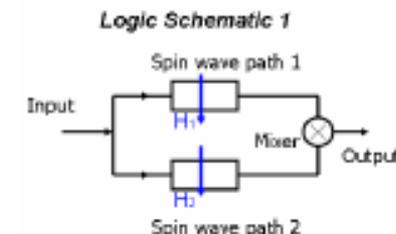
Fabricated structures using PZT and BFO



Design spin wave devices and gates



Structures to reduce Eddy Currents



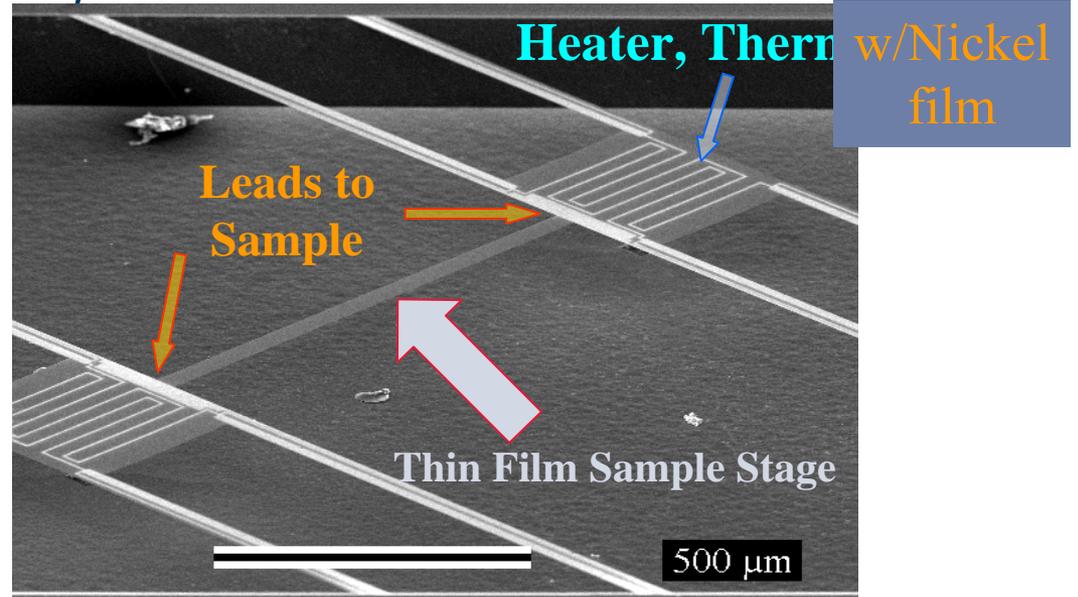
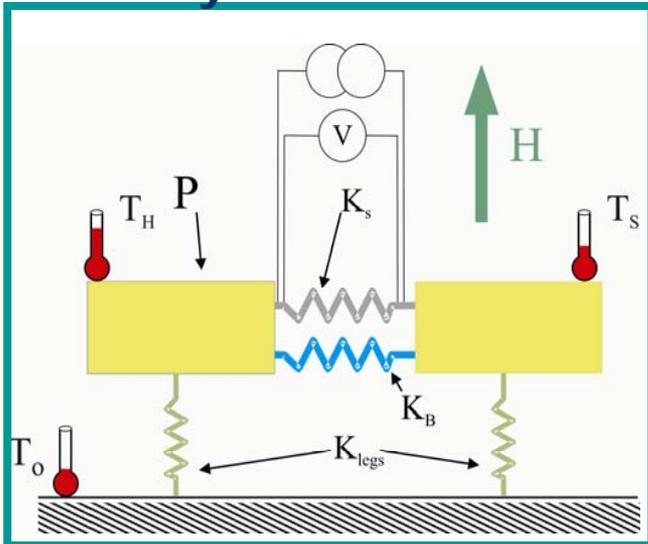
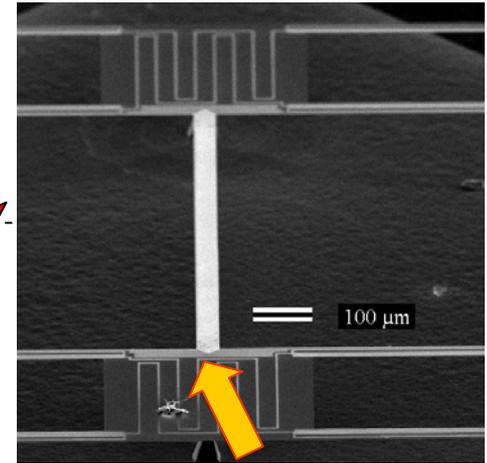
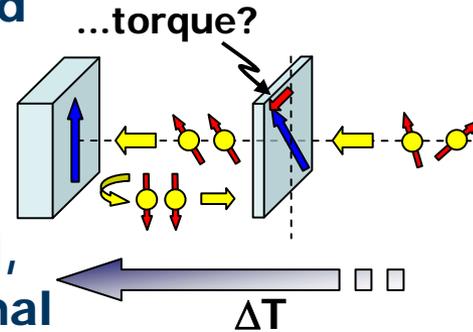
Spin wave circuits (UCSB/UCLA)



Optimize spin wave device

A. Avery, R. Sultan, D. Bassett, B. L. Zink, U. of Denver; M. R. Pufall, NIST

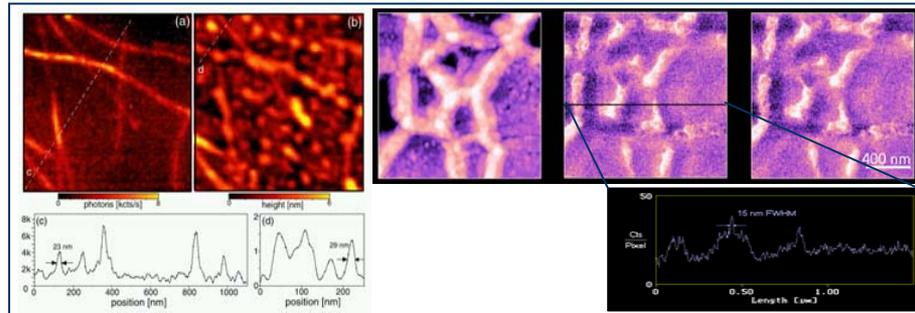
- **Motivation:** Thermal gradients predicted to drive spin-polarized currents and torques in magnetoelectronic nanostructures
- **Goal:** Use novel measurement techniques to quantify the thermal, thermoelectric, and magnetothermal properties of magnetic thin films, multilayers & nanostructures



E.J. Sanchez, Portland State

Background

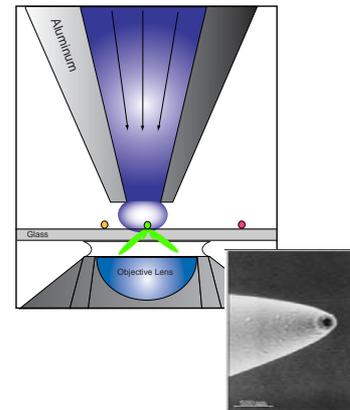
- Due to diffraction, traditional optical microscopy is limited to a resolution of roughly half the wavelength of the incident light.
- Near-field scanning optical microscopy (NSOM) is able to overcome this diffraction limit.
- Tip-enhanced near-field optical microscopy (TENOM), has produced higher resolution images ~10's of nm's.



Left: Simultaneous near-field Raman image (a) and topographic image (b) of SWNT grown by CVD on glass.

Right: 15 nm resolution of photosynthetic membranes (*Spinacea Oleracea*) on glass.

NSOM:



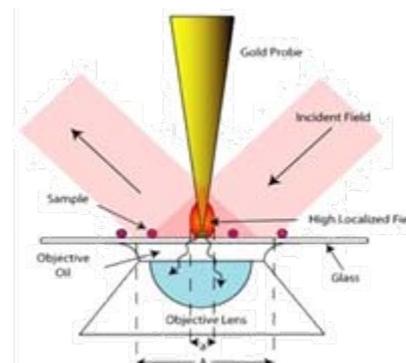
Light propagates thru pulled optical fiber onto surface

Optical signal collected thru fiber

Resolution limited by diam. of aperture (~>50 nm)

Simultaneous illumination/ collection allows for study of non-transmissive samples

TENOM:



Light focused on sharp gold tip 2-5 nm from surface

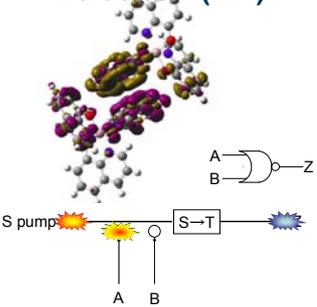
Sample excited by localized field enhancement

Raman/fluorescence imaging

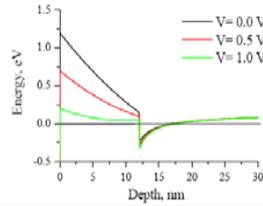
Resolution limited by sharpness of tip (<20 nm)

Better resolution, higher topography

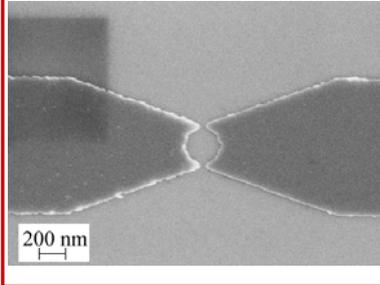
Molecular Excitons Spintronics
Baldo et al (MIT)



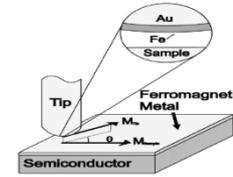
Quantum Dot Modeling
Shur et al (RPI)



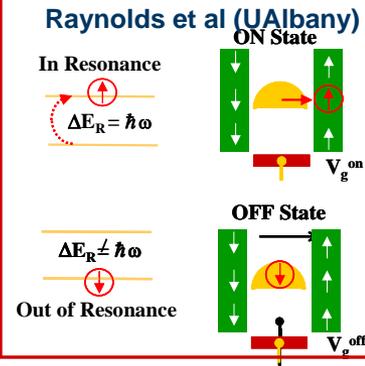
Quantum Dot Devices
Oktyabrsky et al (UAlbany)



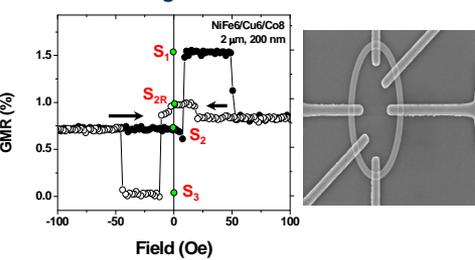
Ballistic Spin Devices
Labella et al (UAlbany)



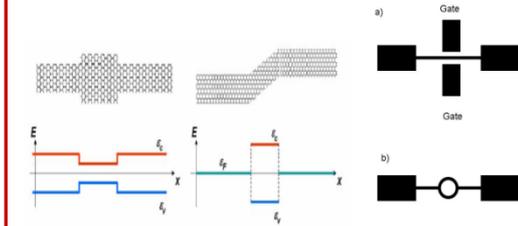
Single Electron Spin Devices
Raynolds et al (UAlbany)



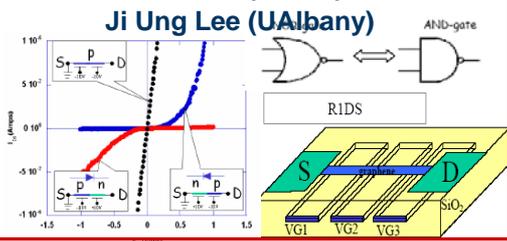
Magneto-electronic Devices
Multi bits logic Ross et al (MIT)



Graphene Nanowire Switches
Murali and DeHeer (GT)

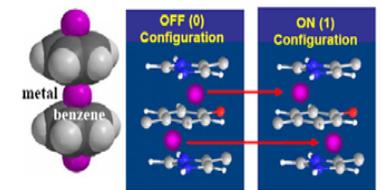


Reconfigurable One-Dimensional (1D) Switch (R1DS)
Ji Ung Lee (UAlbany)

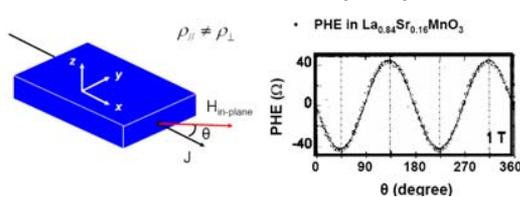


Post CMOS Switches

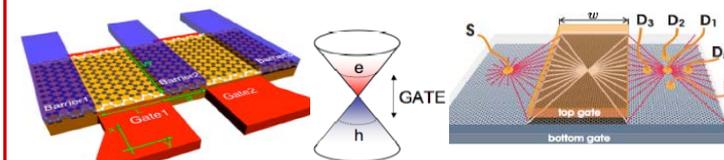
Molecular Nanowire Switches
Kaloyeros et al (UAlbany)



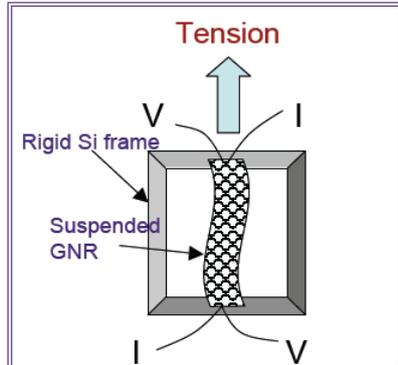
Logic Switches based on Complex Oxides
Ahn et al (Yale)



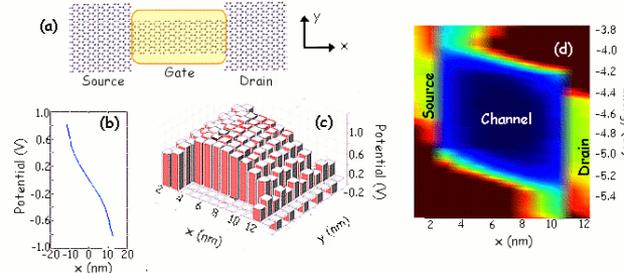
Graphene based Quantum Devices
Charles Marcus (Harvard)



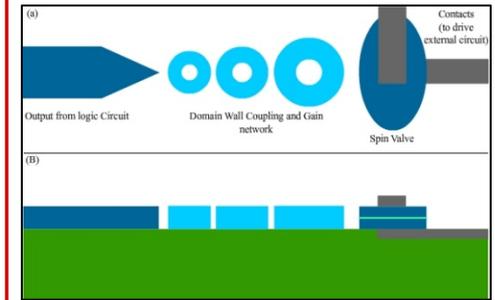
In-situ graphene characterization
Greer (CalTech)



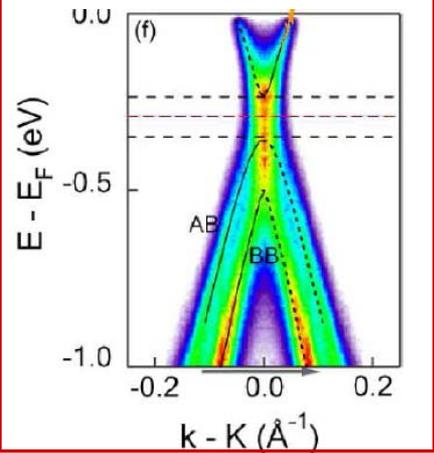
Graphene Circuit Modeling
Stan (UVA)



Magnetic Tunnel Junctions in Nanowires
Misra et al (NCSU)

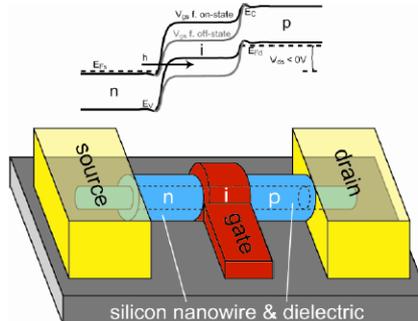


Graphene Metrology
First (GIT)

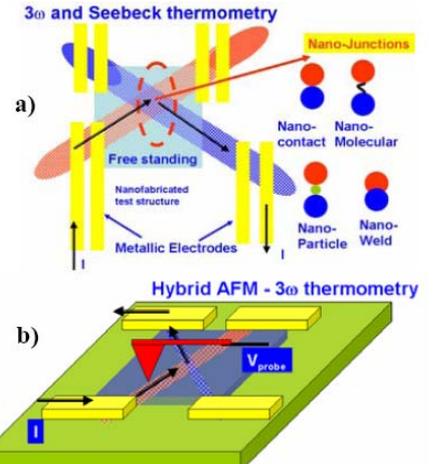


Post CMOS Switches and Metrology

Non-equilibrium FET
Appenzeller (Purdue)

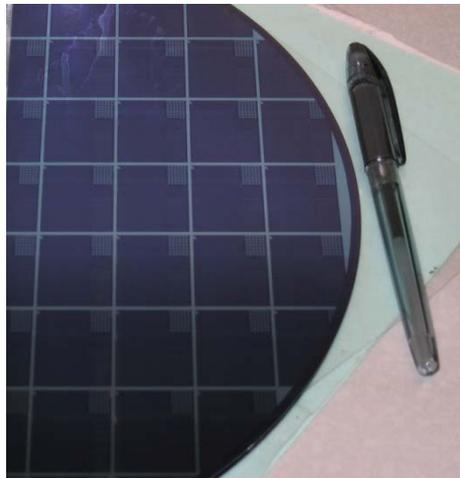


Heat Management
Ramanath et. al. (RPI)

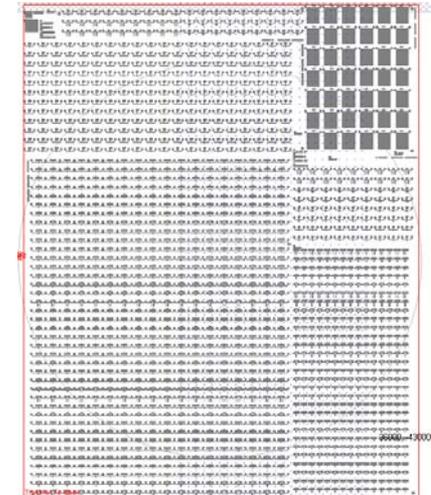
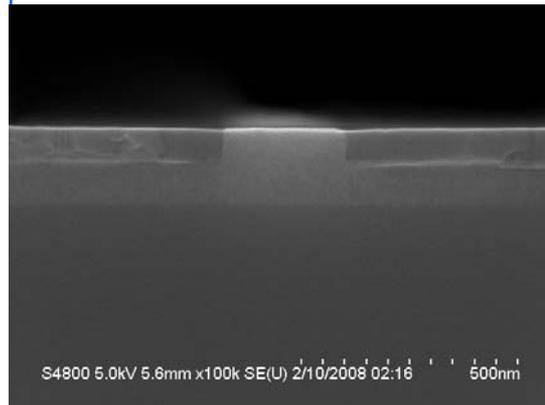


Test Site Design and Fabrication

(0.1+0.1 wafer starts per day from IBM and UAlbany)



- >1000 devices/die
- Advanced processes



Novel Device Integration Capability: Developed test structures and process capabilities for carbon nanotube and graphene post-CMOS devices using advanced 300mm wafer line.

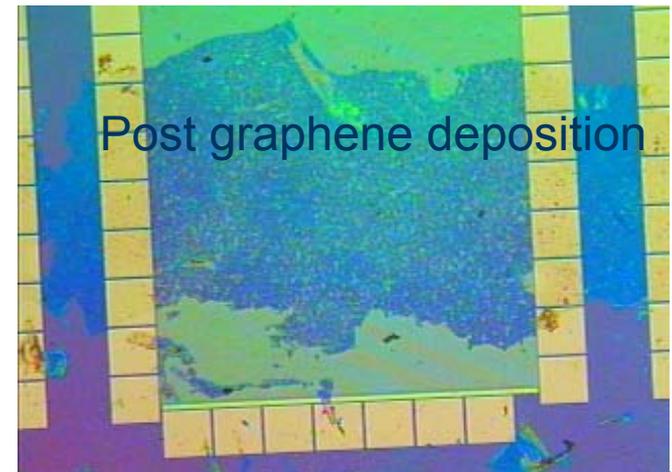
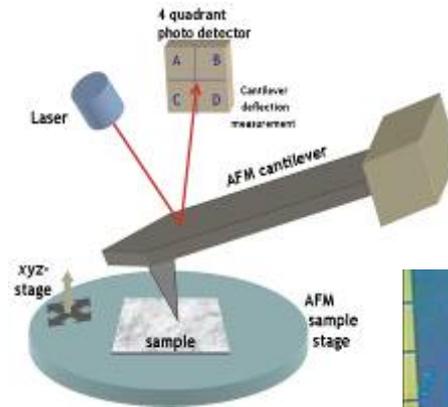
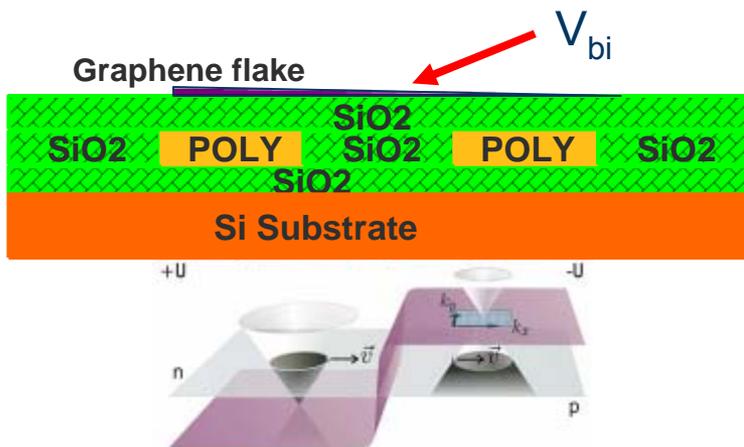
- First run completed for measuring exciton transport in CNTs

NRI Objective: Develop massively parallel scheme for sampling large device and materials parameters.

Robert Geer-UAlbany, Joe Kopanski – NIST



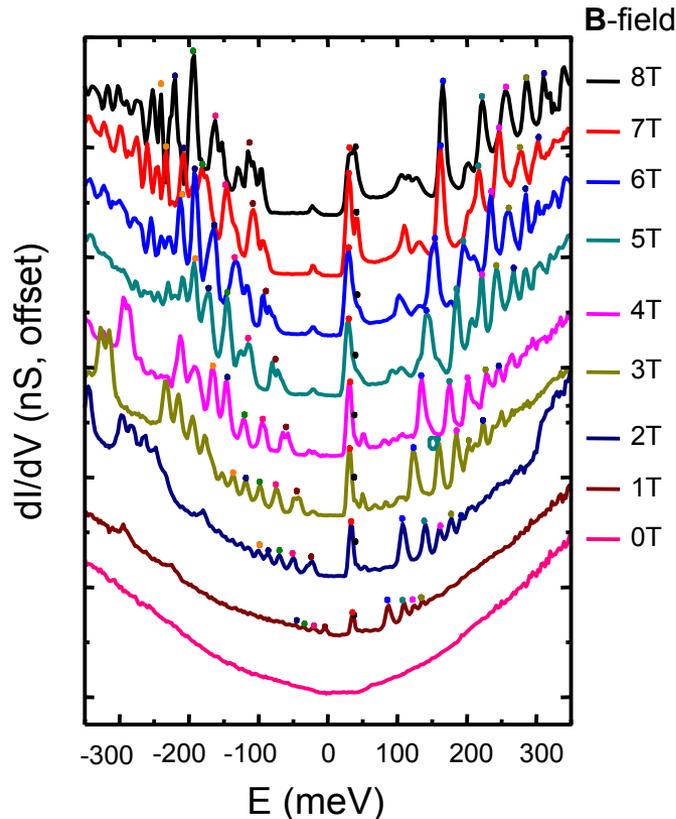
- Kelvin probe microscopy: Electric-force imaging to extract surface potential
- Enables measurement of V_{bi} in conventional semiconductor p-n junctions
- Adapt to electrostatically-doped graphene structures (macro-electrodes)



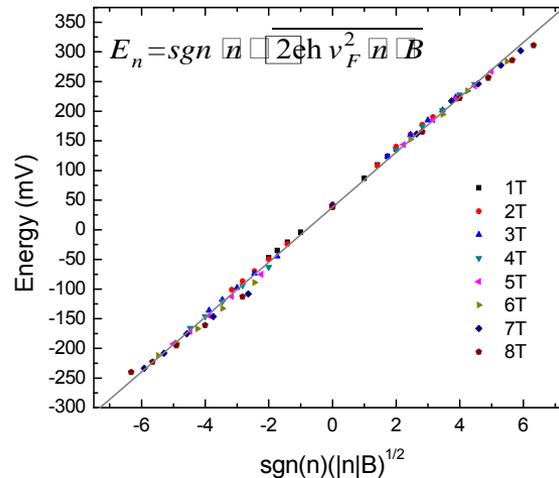
P.N. First (GIT), J.A. Stroscio (NIST)
Material: *W. A. de Heer, GIT*

Rotationally-stacked Multilayer with **Single Layer** Behavior

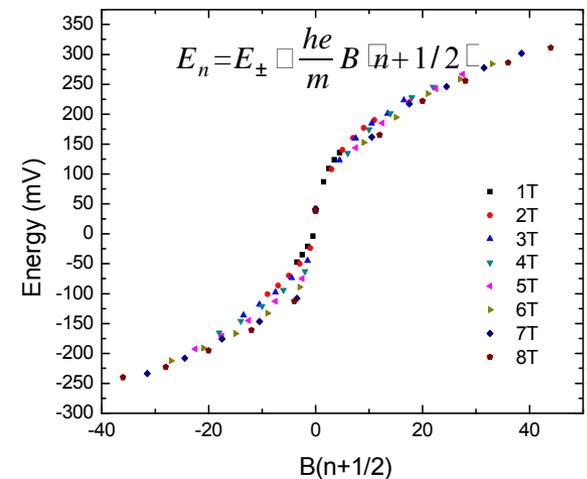
Tunneling spectroscopy of Landau levels
(quantized cyclotron orbits)
shows **graphene** indexing, **not graphite**.



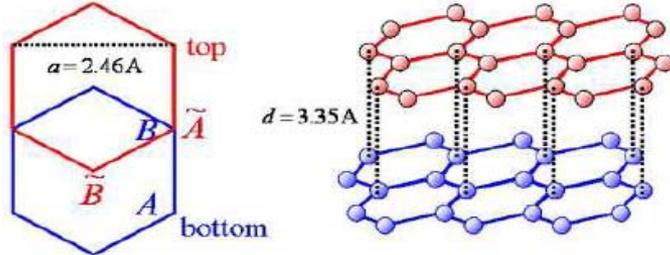
Graphene Indexing



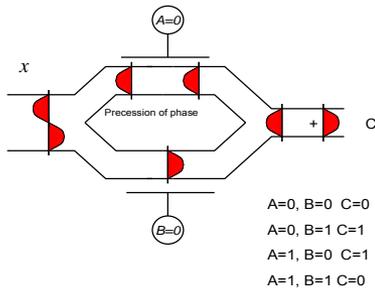
Graphite Indexing



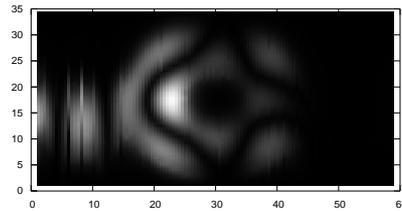
Task 1: Logic Devices with Alternate State Variables



Pseudospintronics on Graphene: UT, UTD, Maryland

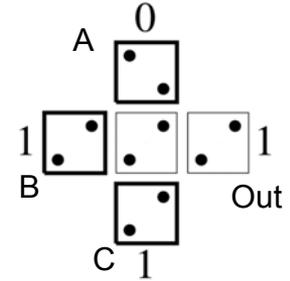
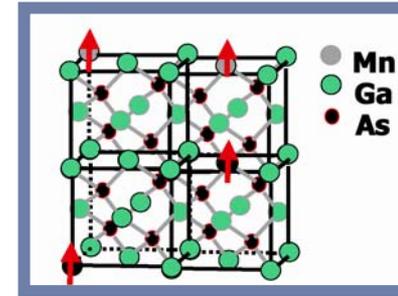


Phasetronics: UT



Path Integral Monte Carlo: ASU

Task 2: Novel Materials and Structures



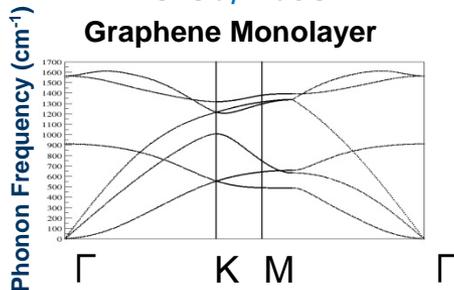
MQCA:ND

DMS: A&M, Maryland, UT

Task 3: Nanoscale Thermal Management

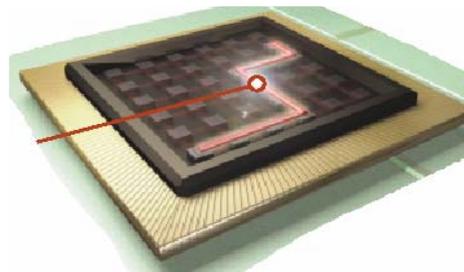
UIUC, NCSU

Graphene Monolayer



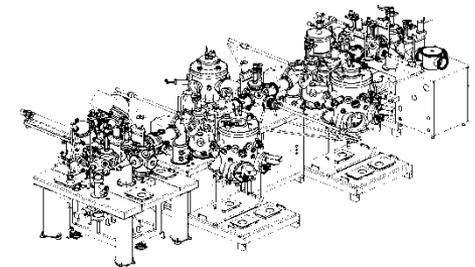
Task 4: Nano plasmonic interconnects

Rice



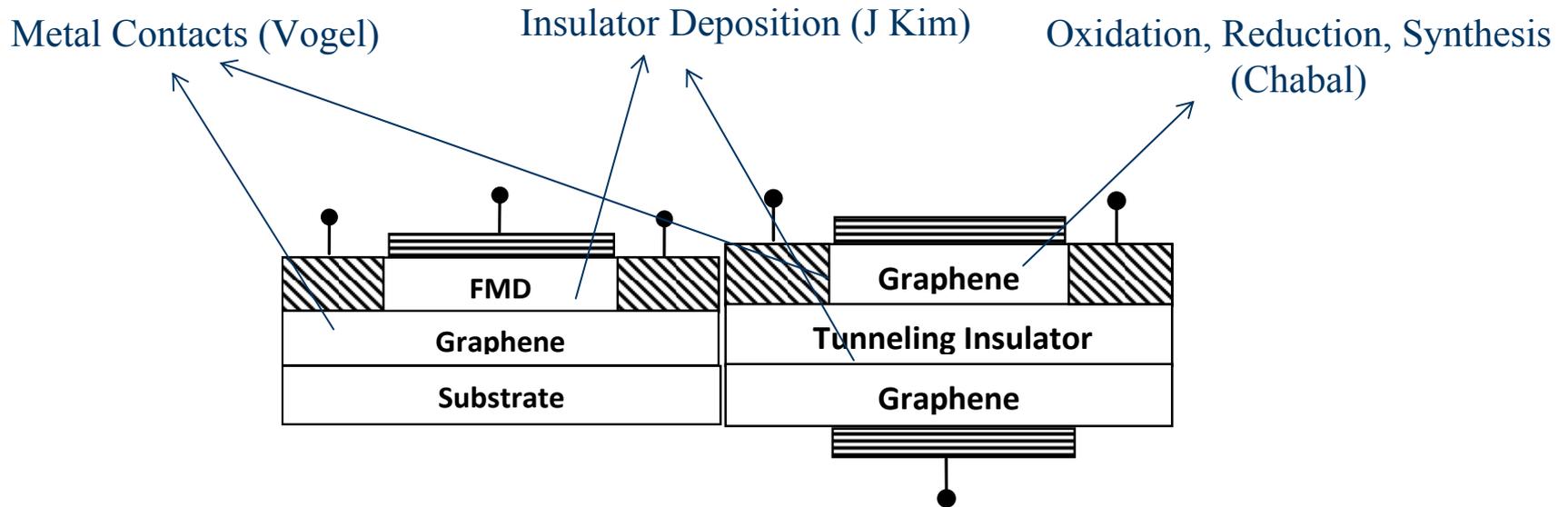
Task 5: Nanoscale Characterization

UTD



Goal of UTD SWAN-Graphene Program:

To develop the materials science, processes, characterization techniques and associated understanding necessary to implement beyond-CMOS graphene-based devices.

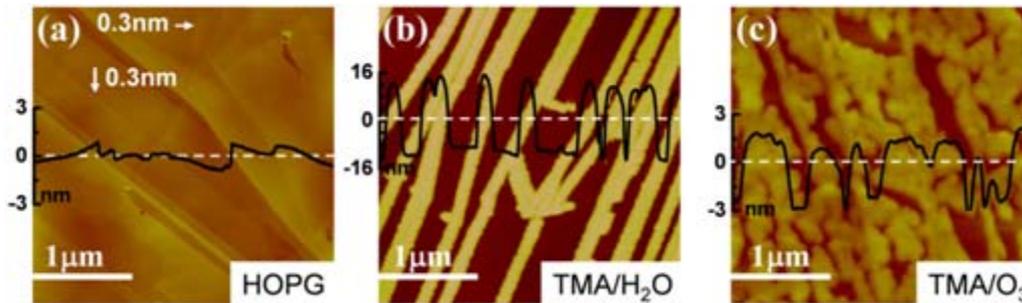


Cross-cutting: Microscopy & Manipulation (M Kim), Surface Science (Wallace), Material Modeling (Cho)

How do real processes and interfaces affect the ideal properties of graphene (e.g. structure, bonding, D.O.S.)?

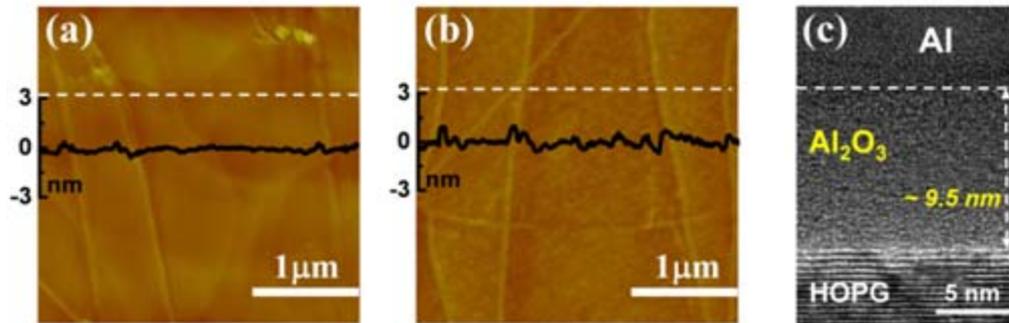
UT-Dallas demonstrated conformal Al₂O₃ ALD on HOPG

• Characteristics of poor ALD-Al₂O₃ layer on the HOPG surface



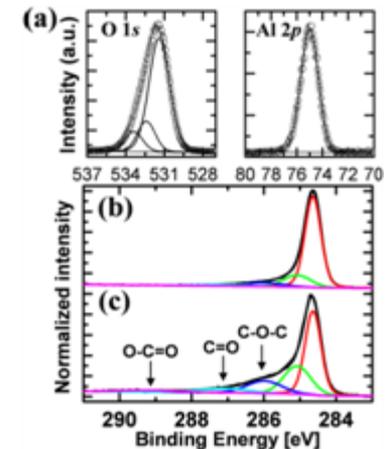
(a) AFM image of fresh HOPG surface (b) the sample with Al₂O₃ layer deposited from TMA/H₂O 200 cycles process (c) with Al₂O₃ layer from TMA/O₃ process 50 cycles.

NRI Significance: Conformal deposition of the ALD-Al₂O₃ layer through functionalization of the HOPG surface using O₃

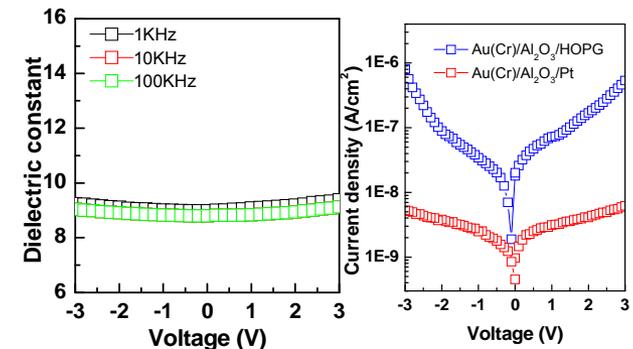


AFM images of (a) the HOPG surface treated by ozone pretreatment, (b) the ALD-Al₂O₃ dielectric (50 cycles) surface on the ozone-treated HOPG, and (c) the cross-sectional HR-TEM image of the Al metal/Al₂O₃ (100 cycles)/the ozone-treated HOPG.

• O₃ treatment functionalizes surface and enables conformal deposition

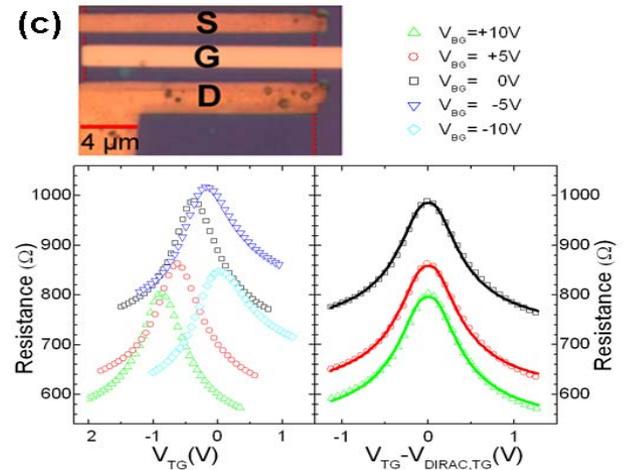
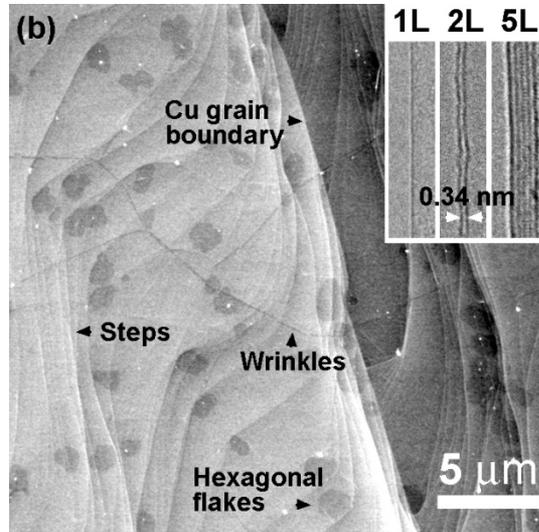
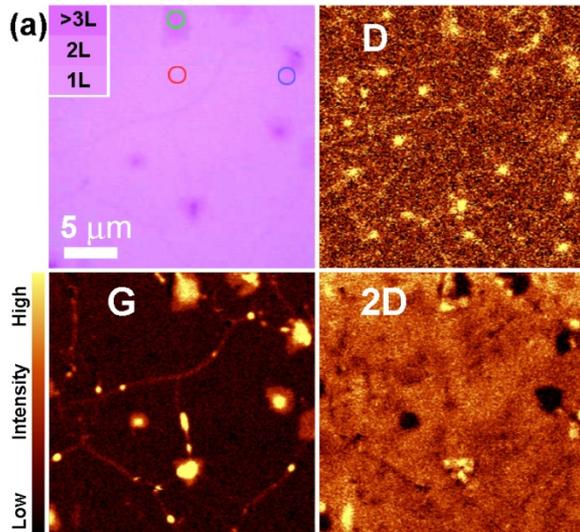
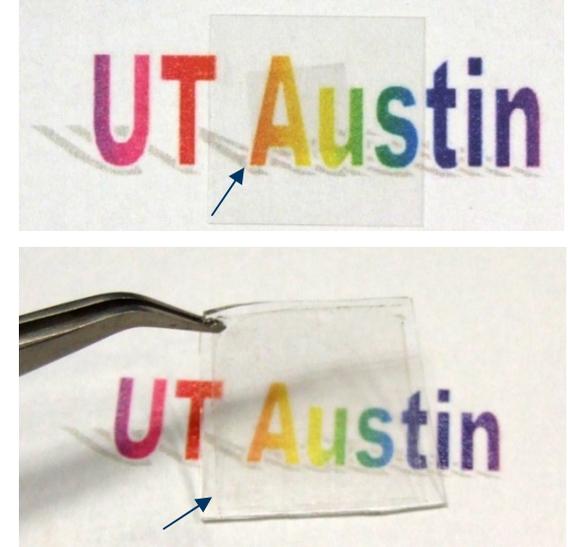
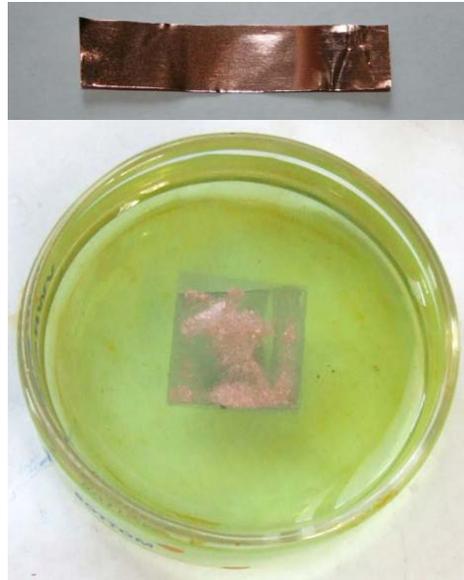
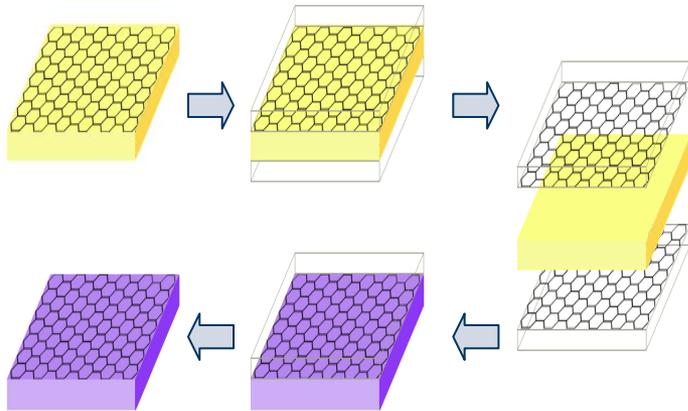


XPS spectra of the Al₂O₃ layer deposited in 50 cycles on top of HOPG treated by ozone (a) O 1s / Al 2p (c) C 1s. (b) XPS spectra of C 1s on the fresh HOPG



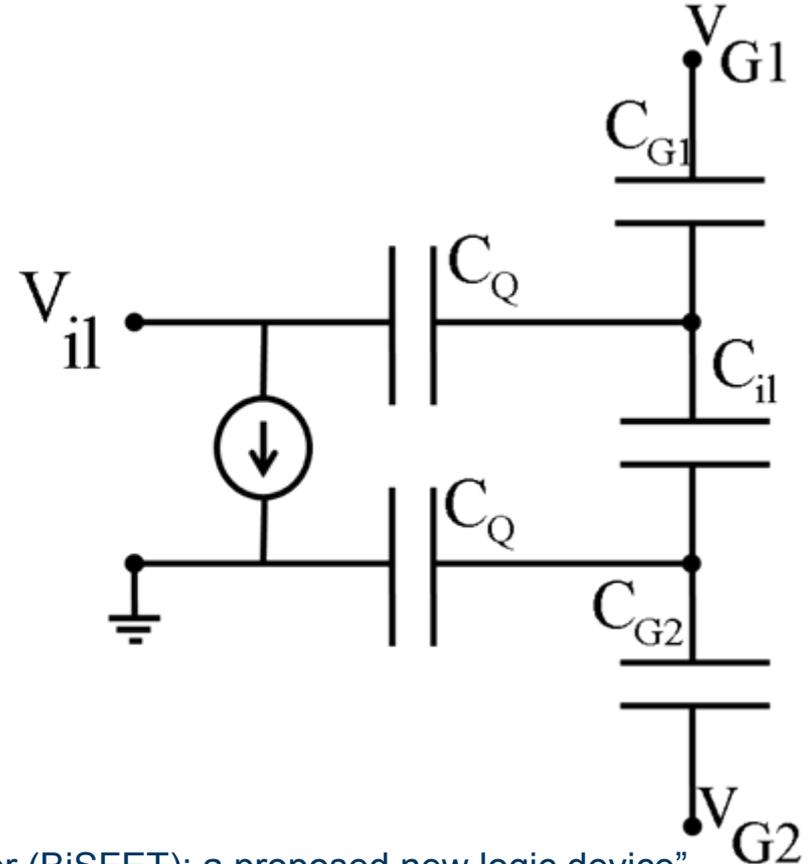
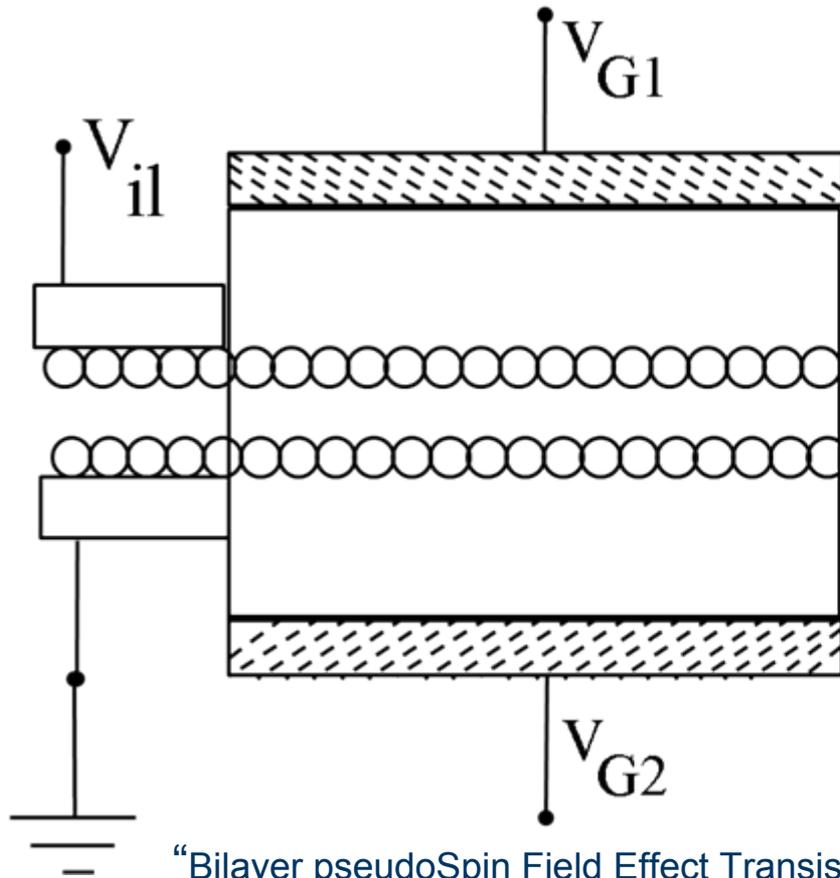
Electrical properties of capacitors incorporating ALD Al₂O₃ films on HOPG demonstrating expected dielectric constant and the associated leakage properties

Transfer



carrier mobility $\sim 4050 \text{ cm}^2 \text{ V}^{-1} \text{ s}^{-1}$,
residual carrier concentration at the Dirac point $n_0 = 3.2 \times 10^{11} \text{ cm}^{-2}$

- Simulated devices and basic logic gates (SPICE)
 - Inverter with complementary BiSFET design simulated at 100 GHz with 25mV operation at just 2x Landauer limit

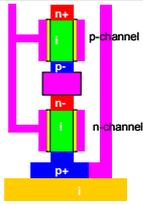


“Bilayer pseudoSpin Field Effect Transistor (BiSFET): a proposed new logic device”
S.K. Banerjee, L.F. Register, E.Tutuc, D.Reddy and A. Macdonald., EDL

Nanoelectronics — Energy-Efficient Devices

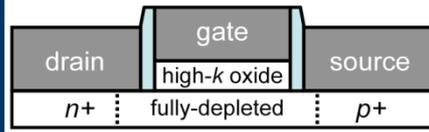
1-Dimensional nanowire interband tunnel transistors

Mayer et al. Penn State



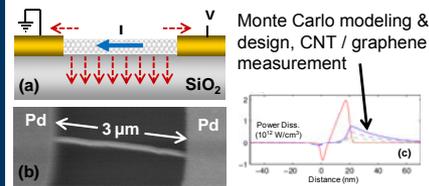
Lateral field-effect tunnel transistors

Fay et al. Notre Dame



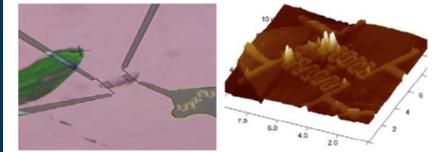
Energy Dissipation in Non-Equilibrium 1/2-D Systems

Pop et al. Illinois



Thermal Transport and Thermal Logic Gates

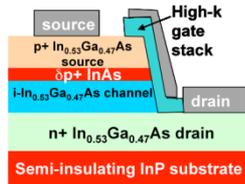
Chen et al. Purdue and NML



Patterned graphene nanostructures

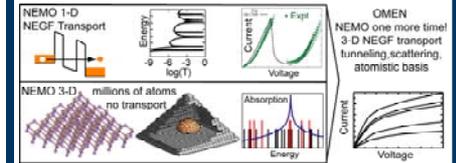
Vertical heterostructure tunnel transistors

Datta et al. Penn State



Full 3-D, 2-D, 1-D Quantum Transport Models

Klimeck et al. Purdue



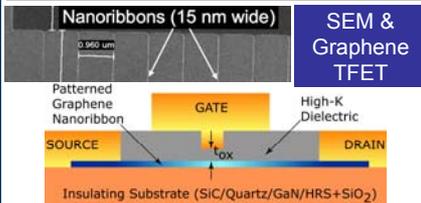
Nanoelectronics • Architectures



MIDWEST INSTITUTE FOR NANOELECTRONICS DISCOVERY

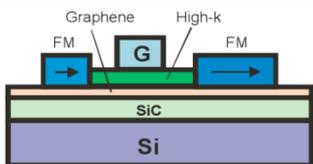
Gated graphene resonant tunneling transistors

Jena et al. Notre Dame



Graphene SpinFETs on Silicon

Ye et al. Purdue and UTD



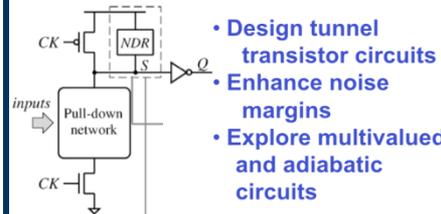
Architectures for emerging NRI devices

Porod et al. Notre Dame

Provide performance comparison of NRI emerging device technologies for benchmarking and for comparison to CMOS technology

Circuit design for emerging NRI technologies

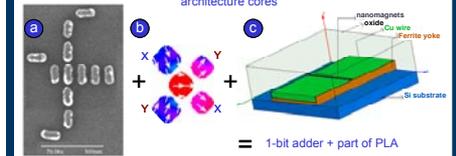
Mazumder, Univ. Michigan



Architectures for nanoscale magnetic logic devices

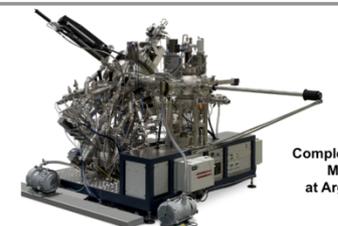
Niemier et al. Notre Dame

Leverage (a) experimental progress, (b) physical-level simulations of new circuit structures, and (c) drive circuitry designs + experiments to fabricate two architecture cores



National Lab Collaborations

NIST – Argonne – NML



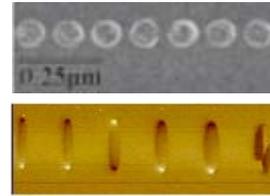
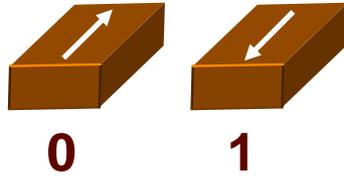
Complex oxide MBE at Argonne

Architectures — Energy-Efficient Systems

Schematic

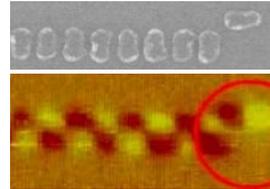
Experimental

Device



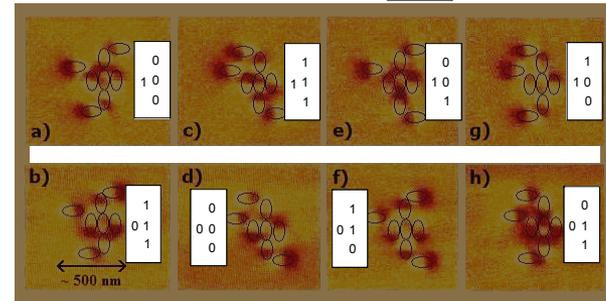
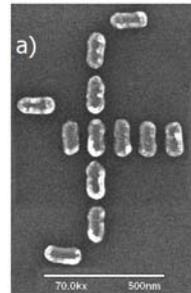
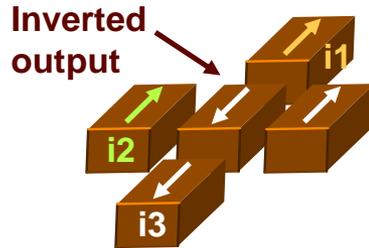
R. Cowburn, M. Welland, "Room temperature magnetic quantum cellular automata," *Science* **287**, 1466, 2000
 A. Imre, "Experimental Study of Nanomagnets for Magnetic QCA Logic Applications," U. of Notre Dame, Ph.D. Dissertation.

Wire



A. Imre, et. al., "Majority logic gate for Magnetic Quantum-Dot Cellular Automata," *Science*, vol. 311, No. 5758, pp. 205–208, January 13, 2006.

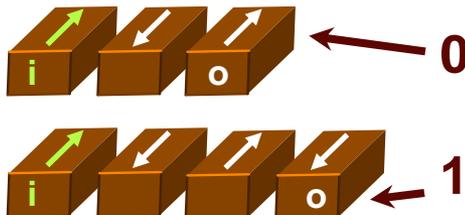
Gate



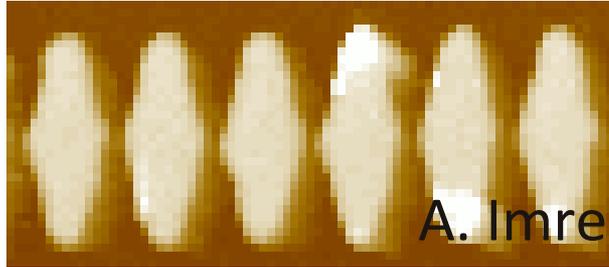
A. Imre, et. al. "Magnetic Logic Devices Based on Field-Coupled Nanomagnets," *NanoGiga* 2007.

A. Imre, et. al., "Majority logic gate for Magnetic Quantum-Dot Cellular Automata," *Science*, vol. 311, No. 5758, pp. 205–208, January 13, 2006.

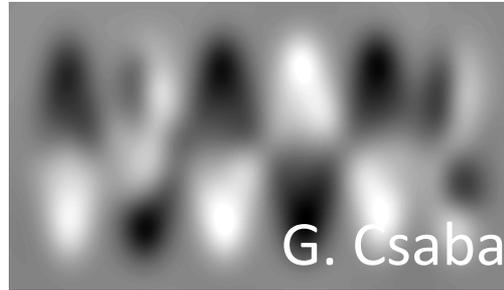
Inverter



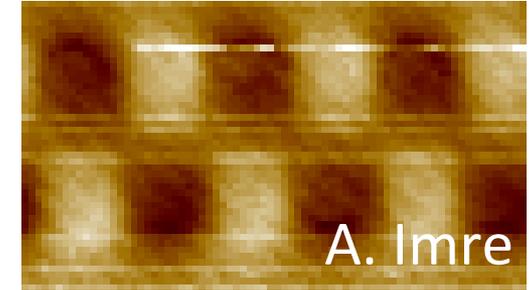
← 1.2 μm →



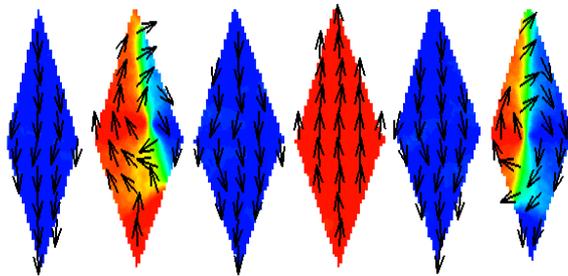
AFM topographic picture



Simulated MFM



Measured MFM



OOMMF simulation

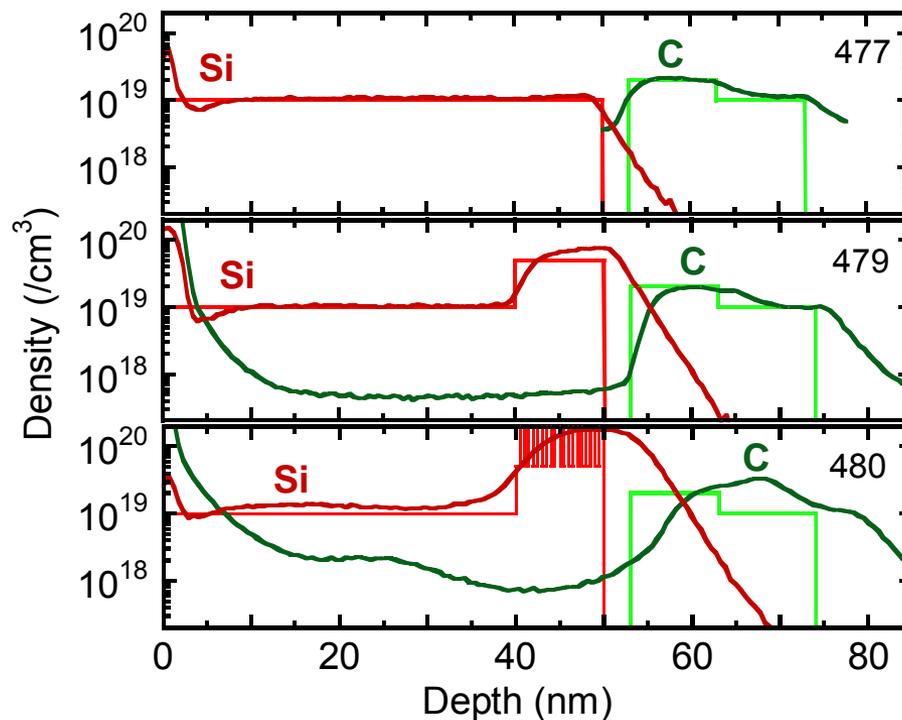
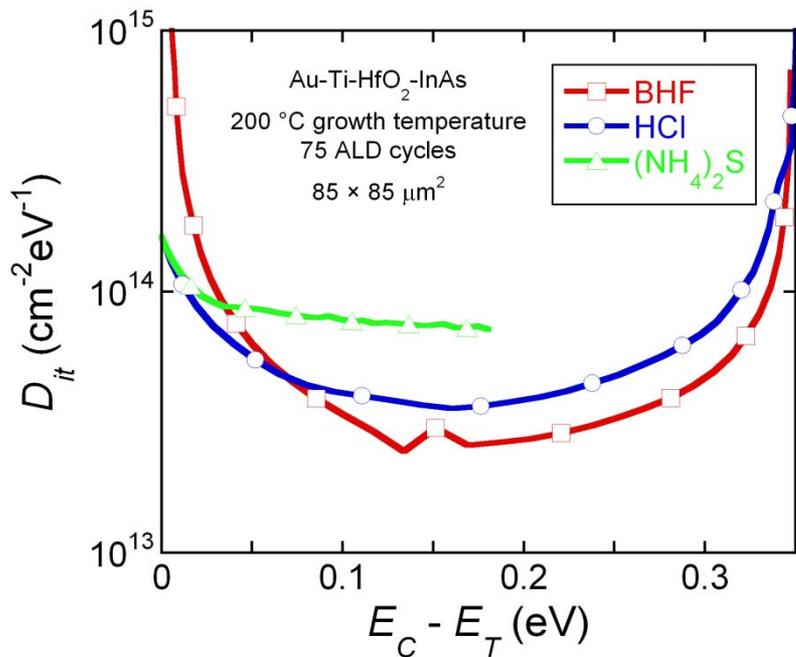
OOMMF – object oriented micromagnetic framework

- Magnetization is routinely mapped using magnetic force microscopy (MFM)
- Quantitative field maps are inferred by comparison with simulation
- Direct nanoscale B/H field measurements are lacking at these scales (e.g. 20 x 40 x 60 nm dots)

*M. Niemier, S. Hu, W. Porod,
G. Bernstein
Notre Dame*

SRC[®] Interface properties and dopant profiles

Field-control of tunneling, spin injection, polarization, ... remain key challenges for post CMOS technologies



- SIMS characterization of InGaAs tunnel junctions: measured vs. target
- Need for electrical profiles with sub-10-nm/decade resolution

- Specific areas of focus for 2009:
 - Room temperature demonstrations of all phenomena
 - Plan to show RT results or a simulation “roadmap” on how to reach RT
 - Accelerate work to demonstrate theory, on simplified structures
 - Theorists provide insight on how to verify effects in “realistic” environments
 - Increase focus on the logic gate / computational system potential
 - How to connect the devices, how to do logic, how to scale functional density
- Increase work on metrology to explicitly link theory to experiment to assess potential devices
 - **Experimentalists**: “What modeling is needed to understand and extrapolate the device potential of current materials/structure/phenomena results?”
 - **Theorists**: “What experiments are needed to constitute a proof-of-concept of your theory or analysis? For example, what experimental work is needed to verify key parameters/assumptions in your model?”
 - **Metrologists**: “How can we measure the critical parameters to bridge between the experimental and simulation results?”

- **Power** will continue as the principal scaling issue for all IC applications
 - CMOS will continue to scale over at least the next decade, with emphasis on utilizing increasing transistor density over increasing frequency

- Any new technology must **overcome the power / performance** limits of a charge-based FET to continue the scaling trend of increased **function / dollar**
 - Does it offer the prospect of lower energy operation / storage?
 - Does it offer the prospect of non-equilibrium (e.g. ballistic) operation?
 - Does it offer the prospect of energy recovery?

- Advancing metrology and characterization techniques is key to the effort to develop any new device
 - “If we can’t measure it, we can’t make it.”

Questions? More Information?

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Allison Hilbert, Executive Assistant
allison.hilbert@src.org